

## **AMENDMENTS TO THE CLAIMS**

### **Listings of Claims**

A listing of the entire set of pending claims is submitted herewith per 37 CFR 1.121. This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Currently amended) A barrier laminate including barrier and planarisation materials for use with a device layer, comprising:

a device layer; and

at least one discontinuous layer of a planarisation material that is external to the device layer and corresponds to a stack including the device layer,

wherein the at least one discontinuous layer is divided into unconnected areas distributed along a plane,

wherein the unconnected areas are separated by regions of a barrier material, and

wherein the barrier material separating the unconnected areas is external to the device layer and is resistant to at least one of water and oxygen permeability such that the device layer is protected against at least one of physical degradation ~~and/or~~ oxidation due to environmental elements.

2. (Canceled)

3. (Previously presented) A barrier laminate according to claim 1, wherein said planarisation material is an organic material.

4. (Previously presented) A barrier laminate according to claim 1, wherein said planarisation material is a combination of organic and inorganic materials.

5. (Previously presented) A barrier laminate according to claim 1, wherein said barrier material is an inorganic material.

6. (Previously presented) A barrier laminate according to claim 1, wherein said regions of a barrier material forms a checked pattern.

7. (Previously presented) A barrier laminate according to claim 1, further comprising at least one continuous layer of a barrier material.
8. (Previously presented) A barrier laminate according to claim 1, wherein said discontinuous layer is arranged between two continuous layers of a barrier material.
9. (Previously presented) A barrier laminate according to claim 1, further comprising at least one continuous layer of a planarisation material.
10. (Previously presented) A barrier laminate according to claim 1, wherein said planarisation material is a polymeric material.
11. (Previously presented) A barrier laminate according to claim 1, wherein said planarisation material is selected from the group consisting of parylene, acrylates, epoxides, urethanes, spin-on dielectrics, and siloxanes.
12. (Previously presented) A barrier laminate according to claim 1, wherein said barrier material is selected from the group consisting of are SiO<sub>2</sub>, SiC, Si<sub>3</sub>N<sub>4</sub>, TiO<sub>2</sub>, HfO<sub>2</sub>, Y<sub>2</sub>O<sub>3</sub>, Ta<sub>2</sub>O<sub>5</sub>, and Al<sub>2</sub>O<sub>3</sub>.
13. (Previously presented) A barrier laminate according to claim 1, wherein the barrier laminate is an oxygen and/or water impermeable film.
14. (Previously presented) A method for the manufacture of a discontinuous layer in a barrier laminate for use with a device layer that includes two opposing electrodes comprising:
  - depositing a continuous layer of a planarisation material;
  - removing regions of said layer of a planarisation material; and
  - filling said regions with a barrier material to form a barrier laminate layer, wherein said regions are external to the device layer and correspond to a stack including the device layer such that the barrier material filling said regions is external to the device layer.

15. (Previously presented) A method for the manufacture of a discontinuous layer in a barrier laminate for use with a device layer that includes two opposing electrodes comprising:

- depositing a patterned layer of a planarisation material, whereby regions where no planarisation material is deposited are formed; and
- filling said regions with a barrier material to form a barrier laminate layer, wherein said regions are external to the device layer and correspond to a stack including the device layer such that the barrier material filling said regions is external to the device layer.

16. (Previously presented) A method according to claim 15, wherein said filling of said regions with a barrier material is performed simultaneously as the deposition of a continuous layer of a barrier material on said discontinuous layer.

17. (Previously presented) A barrier laminate according to claim 1, wherein the at least one discontinuous layer is positioned over active layers of an electronic device and is, among layers of the laminate including planarisation material, closest to the active layers of said electronic device.

18. (Currently amended) The barrier laminate according to claim 1, wherein the device layer includes pixels and wherein the barrier material separating the unconnected areas in the discontinuous layer of planarisation ~~planarisation~~-material is above or below the device layer in the stack.